



BSS84AKQB

50 V, P-channel Trench MOSFET

13 July 2021

Product data sheet

1. General description

P-channel enhancement mode Field-Effect Transistor (FET) in an ultra small DFN1110D-3 (SOT8015) leadless Surface-Mounted Device (SMD) plastic package using Trench MOSFET technology.

2. Features and benefits

- Logic-level compatible
- Side wettable flanks for optical solder inspection
- Ultra small and leadless SMD plastic package: 1.1 x 1 x 0.48 mm
- Trench MOSFET technology
- ElectroStatic Discharge (ESD) protection > 1 kV HBM (Class H1C)
- AEC-Q101 qualified

3. Applications

- Relay driver
- High-speed line driver
- High-side load switch
- Switching circuits

4. Quick reference data

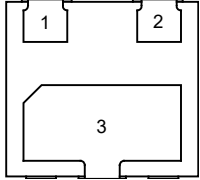
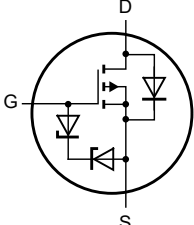
Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{DS}	drain-source voltage	$T_j = 25\text{ }^\circ\text{C}$	-	-	-50	V
V_{GS}	gate-source voltage		-20	-	12	V
I_D	drain current	$V_{GS} = -10\text{ V}; T_{amb} = 25\text{ }^\circ\text{C}$	[1]	-	-270	mA
Static characteristics						
R_{DSon}	drain-source on-state resistance	$V_{GS} = -10\text{ V}; I_D = -100\text{ mA}; T_j = 25\text{ }^\circ\text{C}$	-	3.8	7.5	Ω

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated, mounting pad for drain 6 cm².

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	G	gate	 <p>DFN1110D-3 (SOT8015)</p>	 <p>017aaa259</p>
2	S	source		
3	D	drain		

6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BSS84AKQB	DFN1110D-3	plastic, leadless extremely thin small outline package with side-wettable flanks (SWF); 3 terminals; 0.65 mm pitch; 1.1 mm x 1 mm x 0.48 mm body	SOT8015

7. Marking

Table 4. Marking codes

Type number	Marking code
BSS84AKQB	B9

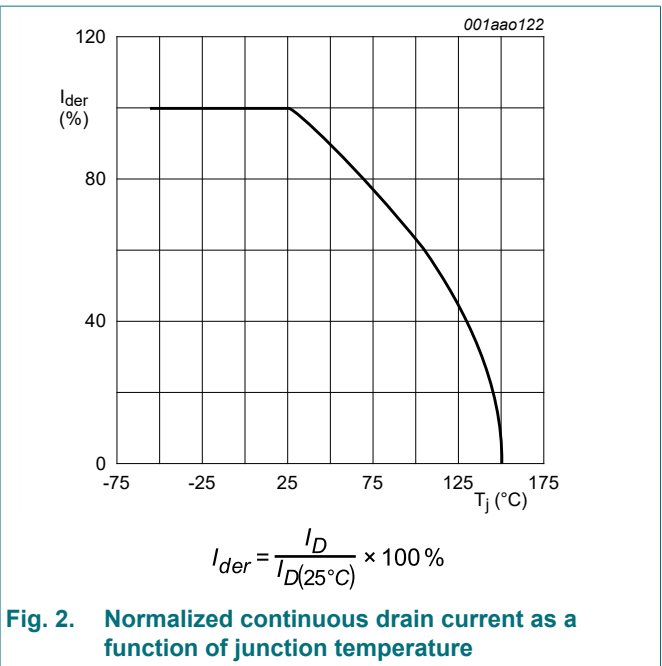
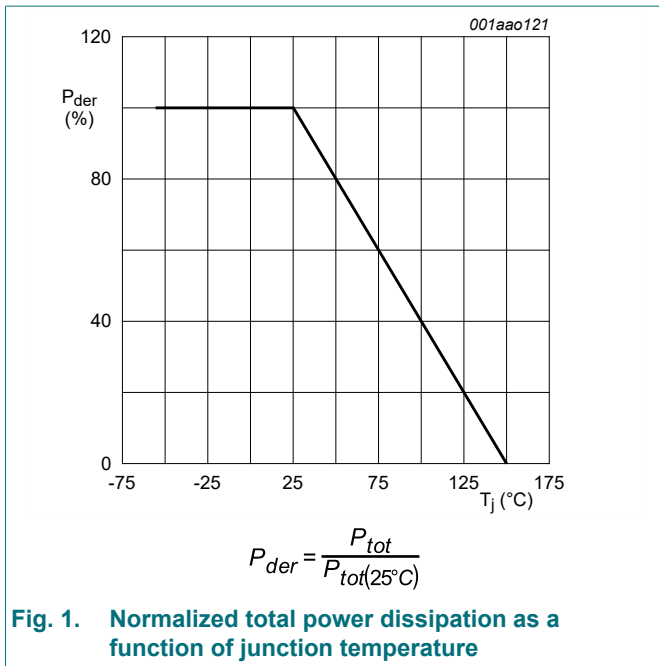
8. Limiting values

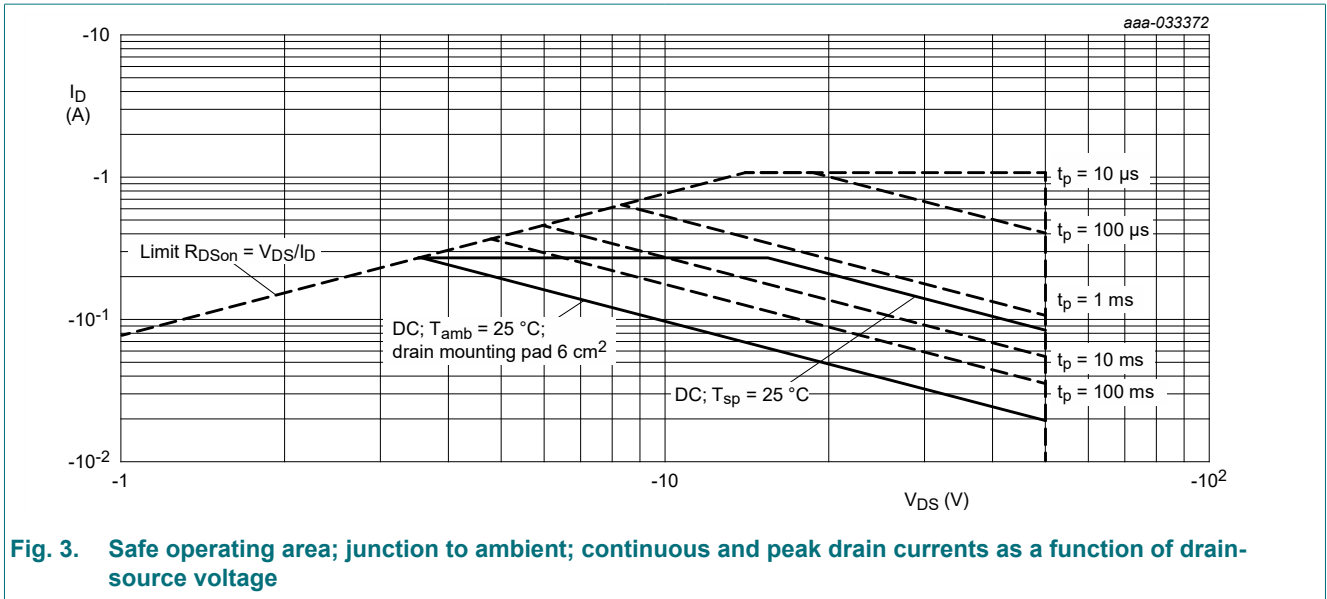
Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit	
V _{DS}	drain-source voltage	T _j = 25 °C	-	-50	V	
V _{GS}	gate-source voltage		-20	12	V	
V _{GSMlim}	peak gate-source voltage	δ _{factor} = 0.1; t _p = 50 μs	-20	20	V	
I _D	drain current	V _{GS} = -10 V; T _{amb} = 25 °C	[1]	-	-270	mA
		V _{GS} = -10 V; T _{amb} = 100 °C	[1]	-	-170	mA
I _{DM}	peak drain current	T _{amb} = 25 °C; single pulse; t _p ≤ 10 μs	-	-1.1	A	
P _{tot}	total power dissipation	T _{amb} = 25 °C	[2]	-	420	mW
			[1]	-	960	mW
		T _{sp} = 25 °C		-	4.2	W
T _j	junction temperature		-55	150	°C	
T _{amb}	ambient temperature		-55	150	°C	
T _{stg}	storage temperature		-65	150	°C	
Source-drain diode						
I _S	source current	T _{amb} = 25 °C	[1]	-	-115	mA
ESD maximum rating						
V _{ESD}	electrostatic discharge voltage	HBM	-	1000	V	
Avalanche ruggedness						
E _{DS(AL)S}	non-repetitive drain-source avalanche energy	T _{j(initial)} = 25 °C; I _D = 0.05 A; DUT in avalanche (unclamped)	-	1.2	mJ	

- [1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated, mounting pad for drain 6 cm².
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.





9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1]	-	245	300	K/W
			[2]	-	110	130	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point			-	25	30	K/W

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for drain 6 cm².

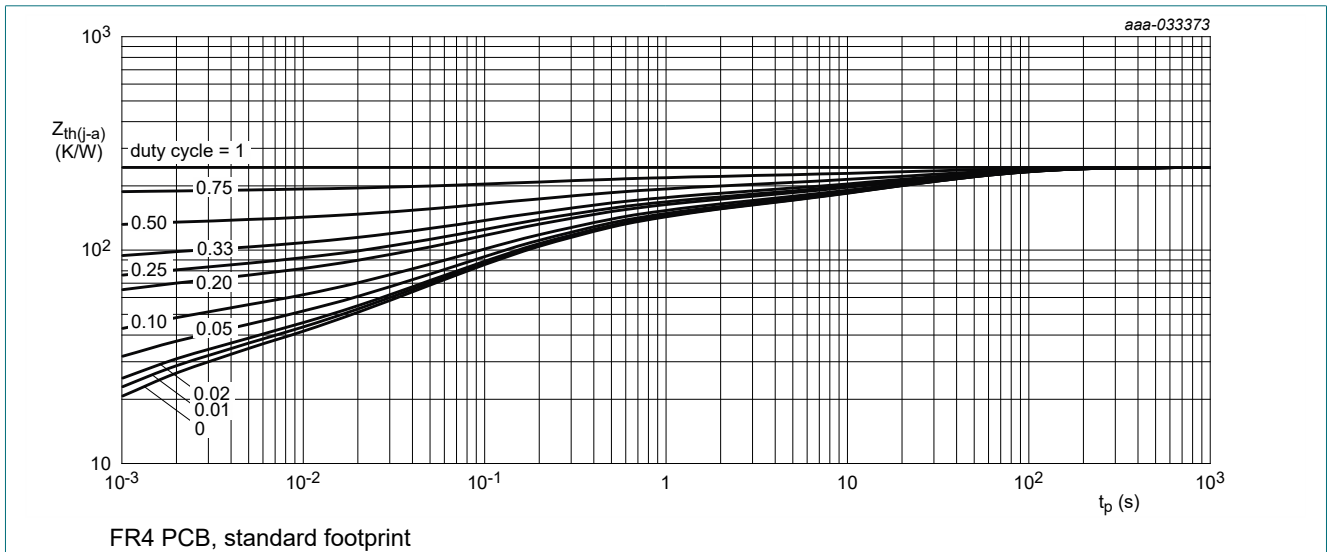


Fig. 4. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

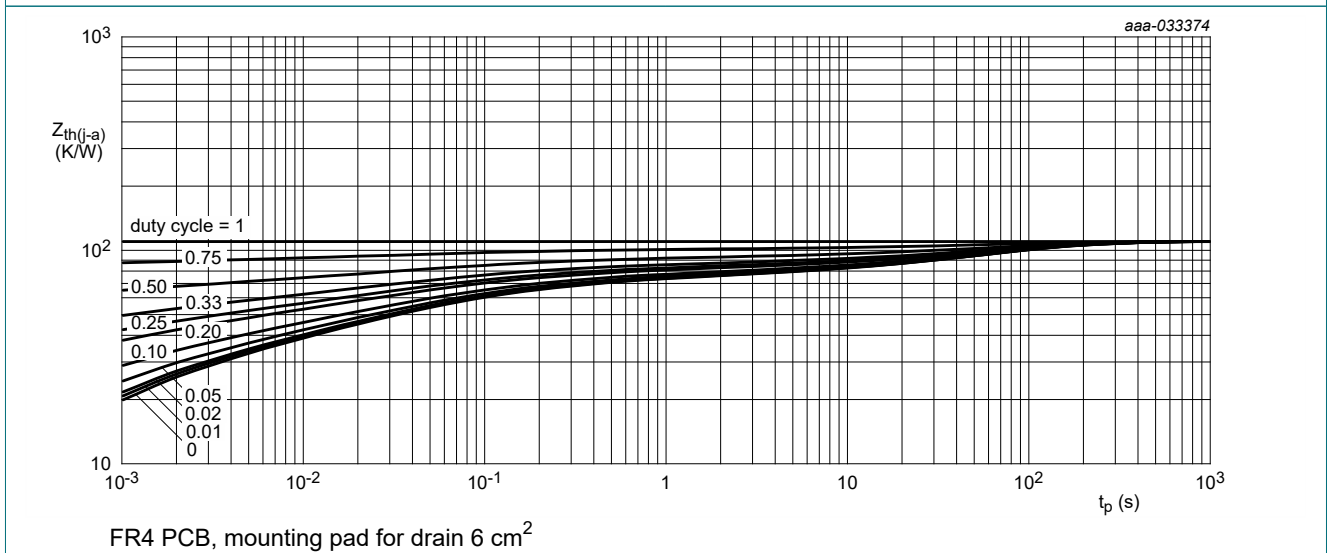


Fig. 5. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
$V_{(BR)DSS}$	drain-source breakdown voltage	$I_D = -250 \mu A$; $V_{GS} = 0 V$; $T_j = 25 \text{ }^\circ C$	-50	-	-	V
V_{GSth}	gate-source threshold voltage	$I_D = -250 \mu A$; $V_{DS} = V_{GS}$; $T_j = 25 \text{ }^\circ C$	-1.1	-1.6	-2.1	V
I_{DSS}	drain leakage current	$V_{DS} = -50 V$; $V_{GS} = 0 V$; $T_j = 25 \text{ }^\circ C$	-	-	-1	μA
I_{GSS}	gate leakage current	$V_{GS} = -20 V$; $V_{DS} = 0 V$; $T_j = 25 \text{ }^\circ C$	-	-	-10	μA
		$V_{GS} = 20 V$; $V_{DS} = 0 V$; $T_j = 25 \text{ }^\circ C$	-	-	10	μA
R_{DSon}	drain-source on-state resistance	$V_{GS} = -10 V$; $I_D = -100 mA$; $T_j = 25 \text{ }^\circ C$	-	3.8	7.5	Ω
		$V_{GS} = -10 V$; $I_D = -100 mA$; $T_j = 150 \text{ }^\circ C$	-	6.7	13	Ω
		$V_{GS} = -4.5 V$; $I_D = -100 mA$; $T_j = 25 \text{ }^\circ C$	-	5	8.5	Ω
g_{fs}	forward transconductance	$V_{DS} = -5 V$; $I_D = -100 mA$; $T_j = 25 \text{ }^\circ C$	-	0.2	-	S
Dynamic characteristics						
$Q_{G(tot)}$	total gate charge	$V_{DS} = -25 V$; $I_D = -0.1 A$; $V_{GS} = -10 V$; $T_j = 25 \text{ }^\circ C$	-	0.4	0.6	nC
Q_{GS}	gate-source charge		-	0.1	-	nC
Q_{GD}	gate-drain charge		-	0.1	-	nC
C_{iss}	input capacitance	$V_{DS} = -25 V$; $f = 1 MHz$; $V_{GS} = 0 V$; $T_j = 25 \text{ }^\circ C$	-	23.2	-	pF
C_{oss}	output capacitance		-	3.5	-	pF
C_{rss}	reverse transfer capacitance		-	1.1	-	pF
$t_{d(on)}$	turn-on delay time		$V_{DS} = -25 V$; $I_D = -0.1 A$; $V_{GS} = -10 V$; $R_{G(ext)} = 6 \Omega$; $T_j = 25 \text{ }^\circ C$	-	6	-
t_r	rise time	-		9	-	ns
$t_{d(off)}$	turn-off delay time	-		40	-	ns
t_f	fall time	-		22	-	ns
Source-drain diode						
V_{SD}	source-drain voltage	$I_S = -0.115 A$; $V_{GS} = 0 V$; $T_j = 25 \text{ }^\circ C$	-	-0.7	-1.2	V
t_{rr}	reverse recovery time	$I_S = -0.1 A$; $dI_S/dt = 100 A/\mu s$;	-	43	-	ns
Q_r	recovered charge	$V_{GS} = -10 V$; $V_{DS} = -25 V$; $T_j = 25 \text{ }^\circ C$	-	39	-	nC

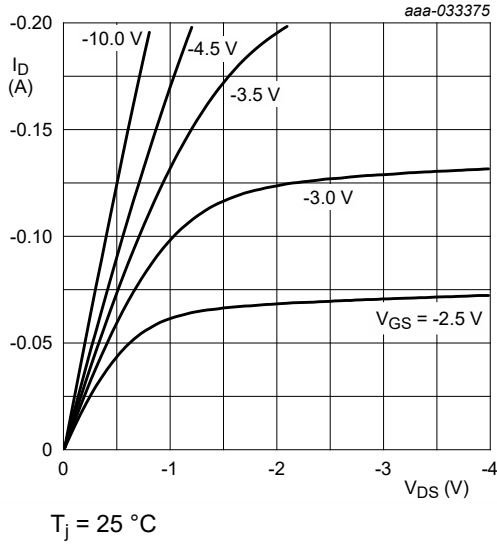


Fig. 6. Output characteristics: drain current as a function of drain-source voltage; typical values

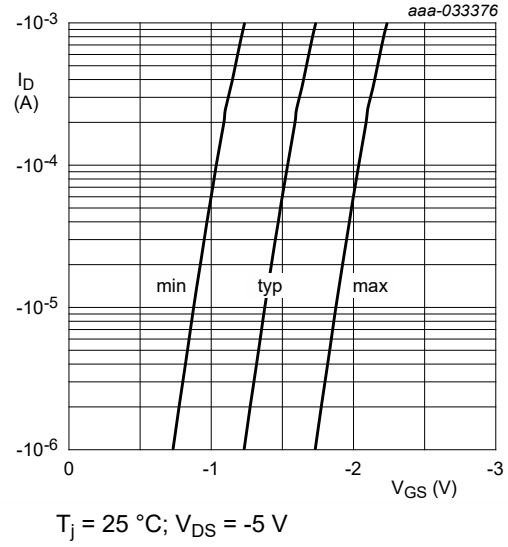


Fig. 7. Sub-threshold drain current as a function of gate-source voltage

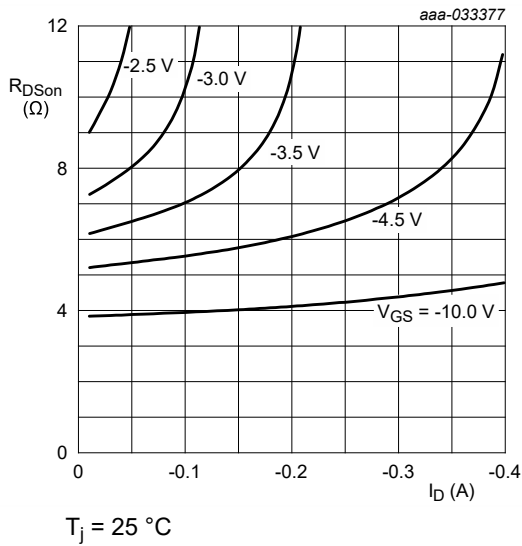


Fig. 8. Drain-source on-state resistance as a function of drain current; typical values

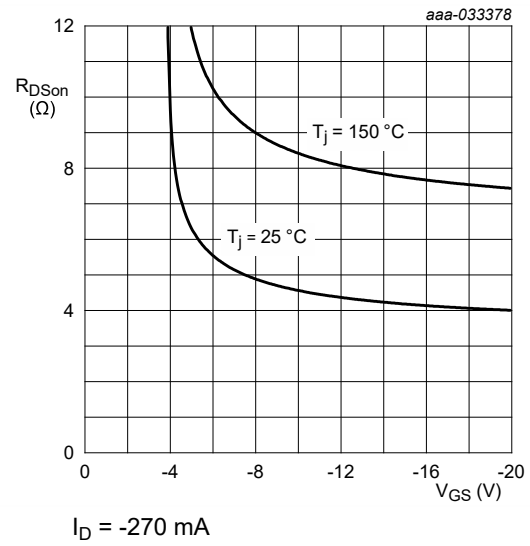


Fig. 9. Drain-source on-state resistance as a function of gate-source voltage; typical values

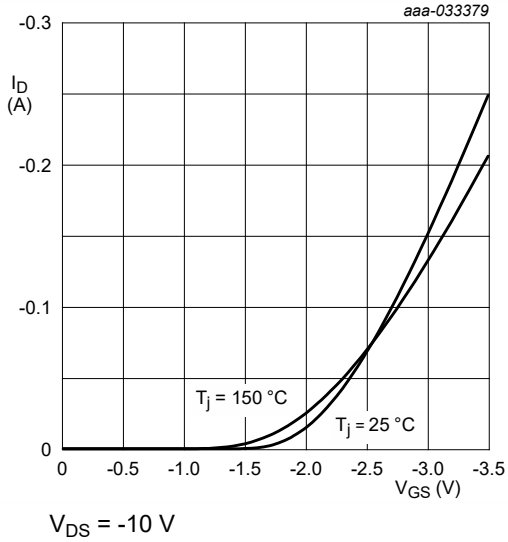
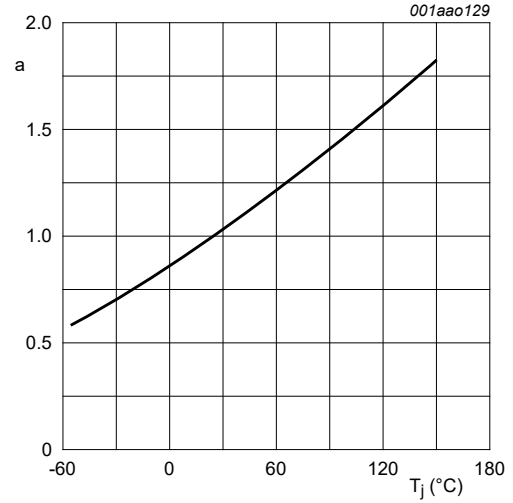


Fig. 10. Transfer characteristics: drain current as a function of gate-source voltage; typical values



$$a = \frac{R_{DSon}}{R_{DSon}(25^\circ\text{C})}$$

Fig. 11. Normalized drain-source on-state resistance as a function of junction temperature; typical values

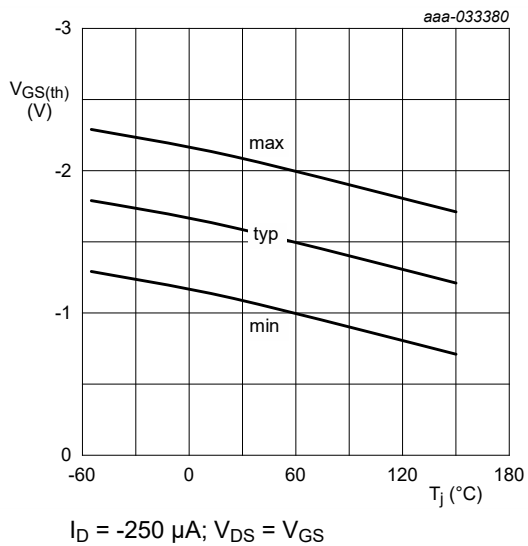


Fig. 12. Gate-source threshold voltage as a function of junction temperature

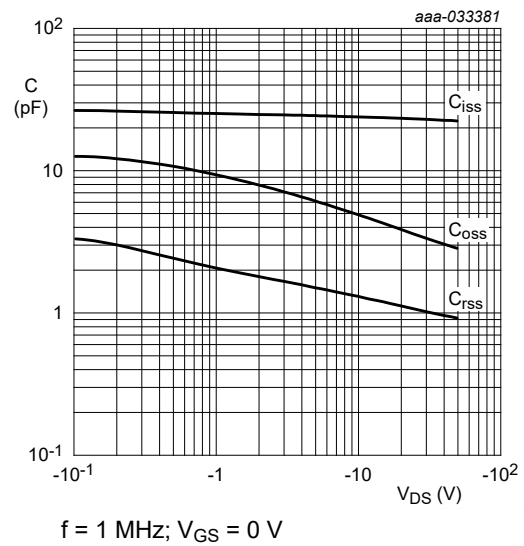
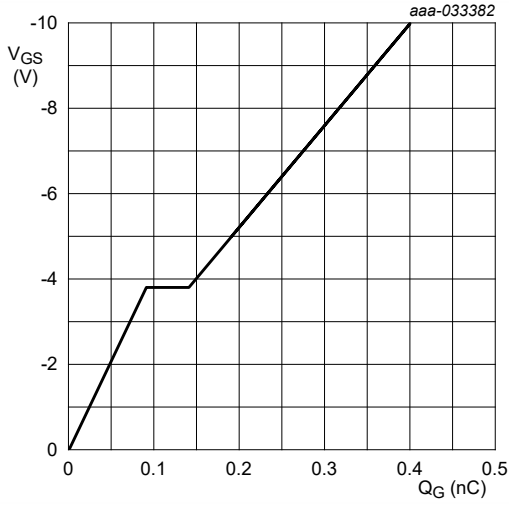


Fig. 13. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values



$I_D = -0.1$ A; $V_{DS} = -25$ V; $T_j = 25$ °C

Fig. 14. Gate-source voltage as a function of gate charge; typical values

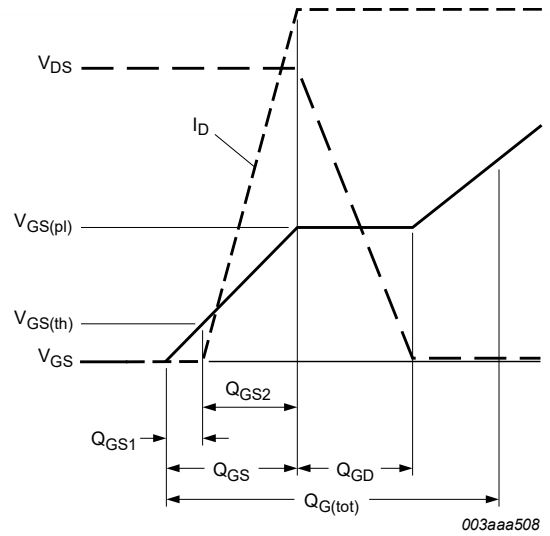
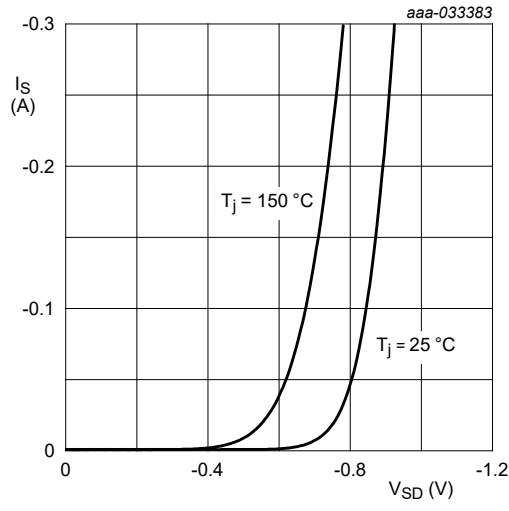


Fig. 15. Gate charge waveform definitions



$V_{GS} = 0$ V

Fig. 16. Source current as a function of source-drain voltage; typical values

11. Test information

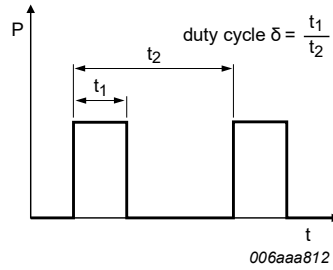


Fig. 17. Duty cycle definition

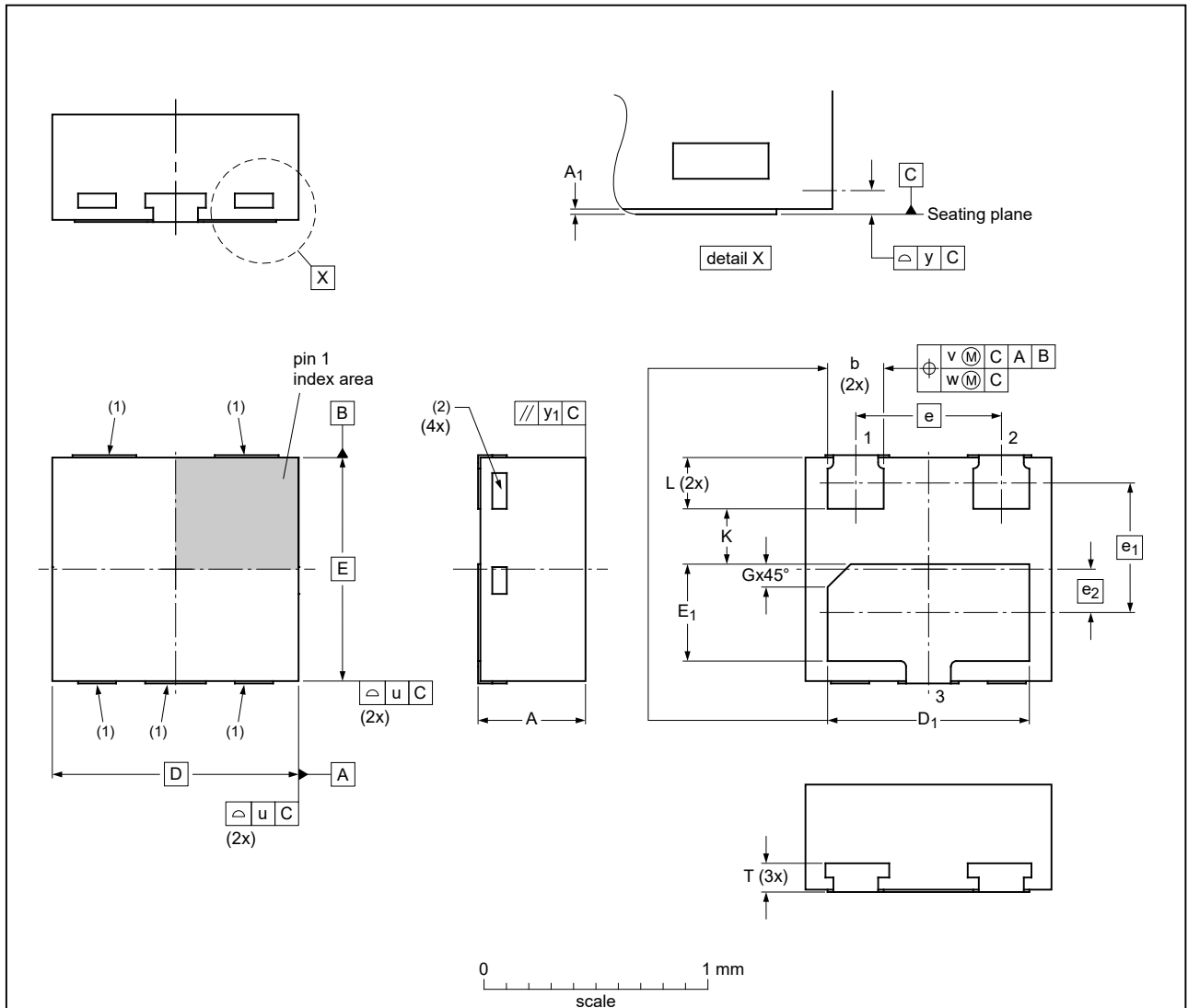
Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - *Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

12. Package outline

DFN1110D-3: plastic, leadless extremely thin small outline package with side-wettable flanks (SWF); 3 terminals; 0.65 mm pitch; 1.1 mm x 1 mm x 0.48 mm body

SOT8015



Dimensions (mm are the original dimensions)

Unit	A	A ₁	b	D	D ₁	E	E ₁	e	e ₁	e ₂	G	K	L	T	u	v	w	y	y ₁
max	0.50	0.040	0.30		0.95		0.48						0.27	0.22					
nom	0.47	0.020	0.25	1.1	0.90	1	0.43	0.65	0.58	0.19	0.09		0.23	0.16	0.05	0.1	0.05	0.05	0.05
min	0.44	0.005	0.22		0.87		0.40				(ref)	0.2	0.20	0.10					

Note

- Side Wettable Flank, protrusion max. 0.02 mm.
 - Visible depend upon used manufacturing technology.
- Dimension A and T are including plating thickness.

sot8015_po

Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
SOT8015		MO-340BA				19-12-02 19-12-04

Fig. 18. Package outline DFN1110D-3 (SOT8015)

13. Soldering

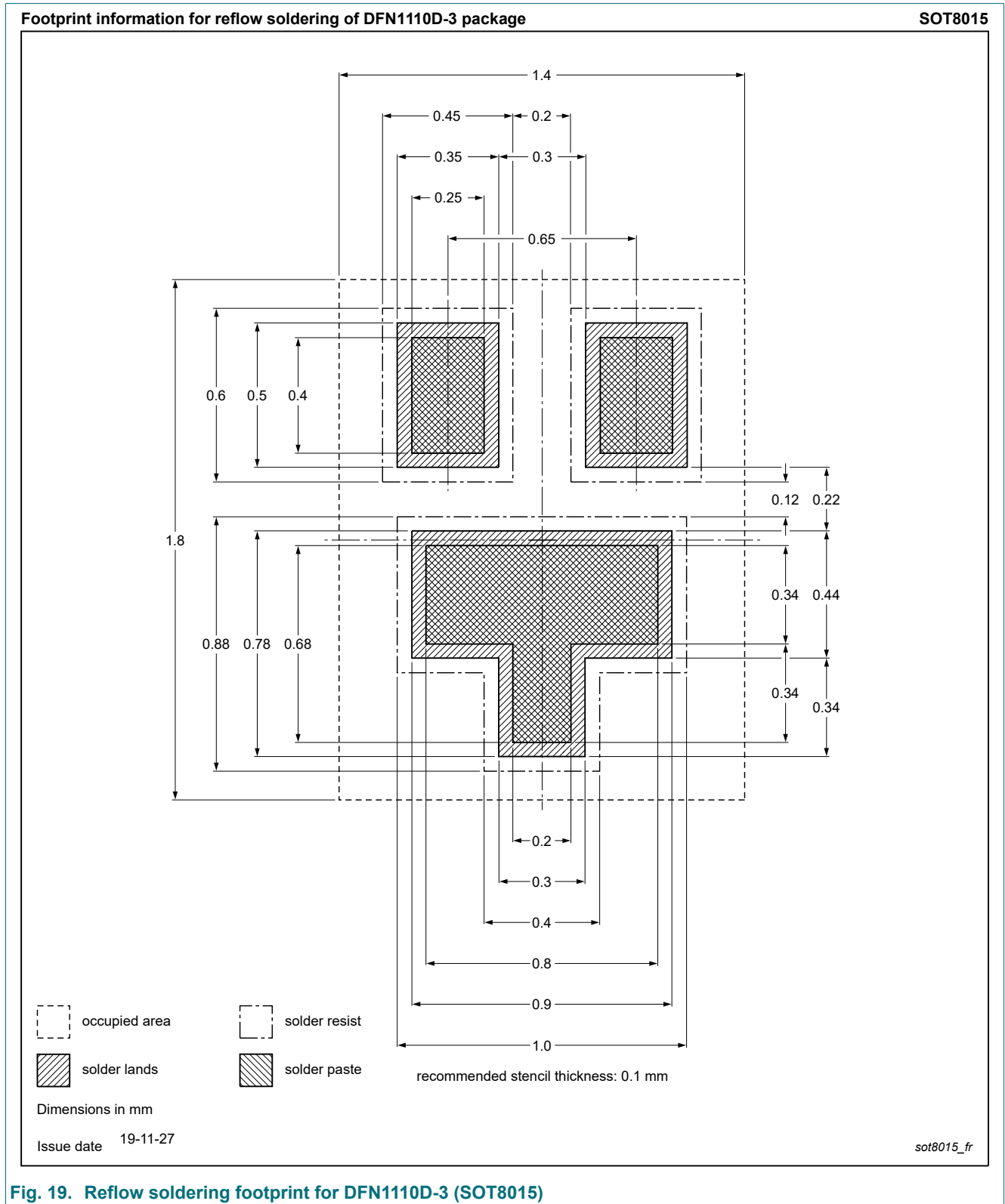


Fig. 19. Reflow soldering footprint for DFN1110D-3 (SOT8015)

14. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
BSS84AKQB v.1	20210713	Product data sheet	-	-

15. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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- [2] The term 'short data sheet' is explained in section "Definitions".
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